

01-20-04

2815

## AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): Wen-Chun ZHENG et al.

Docket No.

03226.111001;P6259

Serial No.

10/085,183

Filing Date

February 27, 2002

Examiner

Chris C. Chu

Group Art Unit

2815

Inventor: **SOLID ASSEMBLY OF FLIP-CHIP PACKAGE ATTACHED TO HEAT REMOVAL DEVICE AND METHOD OF MANUFACTURING SAME**

JAN 16 2004

TO THE COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

## CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	17 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	3 -	3 =	0 x	\$86.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

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<b>CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10)</b> Applicant(s): Wen-Chun ZHENG et al.		Docket No. 03226.111001;P6259	
Serial No. 10/085,183	Filing Date February 27, 2004	Examiner Chris C. Chu	Group Art Unit 2815

Invention: **SOLID ASSEMBLY OF FLIP-CHIP PACKAGE ATTACHED TO HEAT REMOVAL DEVICE AND METHOD OF MANUFACTURING SAME**

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